

A/F/1763

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I hereby certify that this correspondence is being sent via U.S. Mail in an envelope addressed to the Assistant Commissioner for Patents, Box AF, Washington, D.C. 20231 on July 18, 2001.

Signed: Marie L. Cermeli
Marie L. Cermeli



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Yao, et al.

Serial No. 09/457,929

Filed: December 8, 1999

For: WAFER CARRIER AND
SEMICONDUCTOR APPARATUS
FOR PROCESSING A
SEMICONDUCTOR SUBSTRATE

Examiner: Jeffrie R. Lund

Group Art Unit: 1763

San Francisco, CA 94111

Date: July 18, 2001

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Box AF
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This is submitted in response to the Final Office Action mailed May 21, 2001 for the above-identified application, and is timely filed within the shortened statutory period set for response. Applicants respectfully request reconsideration of the above-identified application in view of the following amendments and remarks.

IN THE SPECIFICATION

Please replace the paragraph beginning at page 7, line 3, with the following rewritten paragraph:

--To maintain the desirable line or point contact with the peripheral edge of the wafer and to provide secure support of the wafer, the thermal expansion of the wafer carrier is considered. Preferably, little thermal expansion occurs during the process so that the desired angle of the incline is preserved. Specifically, the wafer carrier is comprised of a material having an isotropic coefficient of thermal expansion in the range of $2.6 \times 10^{-6}/^{\circ}\text{C}$ to $5 \times 10^{-6}/^{\circ}\text{C}$, with the lower values preferred. Materials with suitable coefficients of thermal expansion include silicon and silicon carbide.--